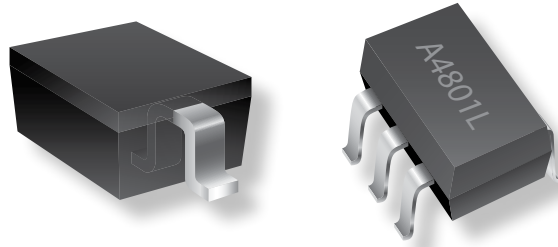


Product Change Notification

TVS DIODES



March 27, 2019

Bourns® TVS Diode and TVS Diode Array Series

Change to Wafer Size and Process Sequence

In order to support our fast growing demand and secure continuity of supply for our customers, the Bourns® TVS Diode and TVS Diode Array products listed below will now be built on 5-inch wafers instead of 4-inch wafers. The wafers will be processed using new 5-inch capable furnaces and equipment, with optimized 5-inch wafer process steps. This change in the size of the wafer and wafer process steps will improve manufacturability of the affected products. There will be no change to the form, fit, function, quality or reliability of the products.

Affected Part Numbers

CDSOD323-T05L	CDSOD323-T08C	CDSOT23-SRV05-4
CDSOD323-T05C	CDSOD323-T08LC	CDSOD323-T12C
CDSOD323-T05LC	CDSOD323-T08L	
CDSOD323-T05	CDSOD323-T08	

Evaluation samples will be available on **April 1, 2019**.

Implementation dates are as follows:

Date that manufacturing using 4-inch wafers will cease: **July 30, 2019**

Date that deliveries of products using 5-inch wafers will begin: **August 1, 2019**

First date code using the 5-inch wafers: **1914**

If you have any questions or need additional information, please feel free to contact [Customer Service/ Inside Sales](#).